Record Nr. UNINA9910973270203321 Autore Gilman John J (John Joseph) **Titolo** Electronic basis of the strength of materials / / John J. Gilman Cambridge:,: Cambridge University Press,, 2003 Pubbl/distr/stampa **ISBN** 1-107-12771-8 0-521-07894-6 1-280-41734-X 9786610417346 1-139-14548-7 0-511-17872-7 0-511-05966-3 0-511-33060-X 0-511-54124-4 0-511-06810-7 Edizione [1st ed.] Descrizione fisica 1 online resource (x, 280 pages) : digital, PDF file(s) Disciplina 620.1/12 Soggetti Strength of materials Electronic structure Lingua di pubblicazione Inglese Materiale a stampa **Formato** Livello bibliografico Monografia Title from publisher's bibliographic system (viewed on 05 Oct 2015). Note generali Nota di bibliografia Includes bibliographical references and index. 1. Nature of elastic stiffness -- 2. Generalized stress -- 3. Generalized Nota di contenuto strain -- 4. Elastic coefficients -- 5. Properties of electrons -- 6. Quantum states -- 7. Periodic patterns of electrons -- 8. Heisenberg's Principle -- 9. Cohesion of atoms -- 10. Intramolecular cohesion --11. Intermolecular cohesion -- 12. Bulk modulus -- 13. Shear moduli -- 14. Entropic elasticity (polymers) -- 15. Universality and unification -- 16. Macroscopic plastic deformation -- 17. Microscopic plastic deformation -- 18. Dislocation mobility -- 19. Mechanics of cracks --20. Surface and interfacial energies -- 21. Fracturing rates. Sommario/riassunto This 2003 book relates the complete set of strength characteristics of constituent atoms to their electronic structures. These relationships require knowledge of both the chemistry and physics of materials. The book uses both classical and quantum mechanics, since both are

needed to describe these properties, and begins with short reviews of each. Following these reviews, the three major branches of the strength of materials are given their own sections. They are: the elastic stiffnesses; the plastic responses; and the nature of fracture. This work will be of great value to academic and industrial research workers in the sciences of metallurgy, ceramics, microelectronics and polymers. It will also serve well as a supplementary text for the teaching of solid mechanics.